

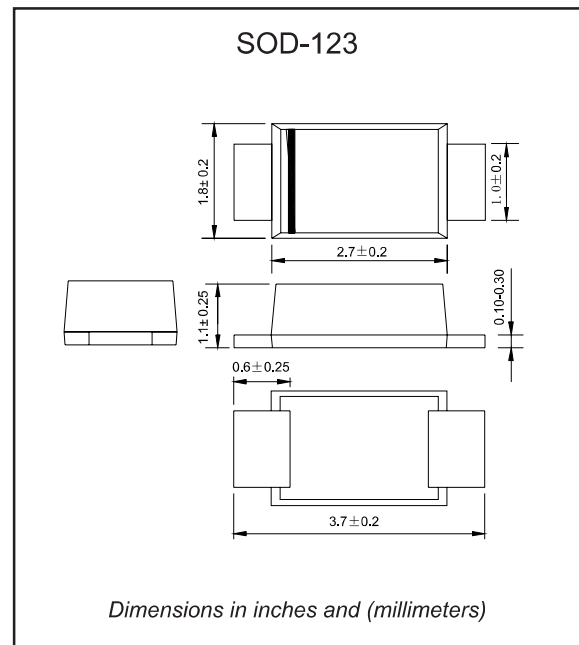
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

### Mechanical data

- ◆ **Case**: JEDEC SOD-123 molded plastic body
- ◆ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	SYMBOLS	DSK32	DSK33	DSK34	DSK35	DSK36	DSK38	DSK310	DSK315	DSK320	UNITS
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V <sub>RMS</sub>	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V <sub>DC</sub>	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at T <sub>L</sub> (see fig.1)	I <sub(av)< sub=""></sub(av)<>	3.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	60.0									A
Maximum instantaneous forward voltage at 3.0A	V <sub>F</sub>	0.55			0.70		0.85		0.92		V
Maximum DC reverse current at rated DC blocking voltage	I <sub>R</sub>	0.5			0.1						mA
		10.0			5.0		2.0				
Typical junction capacitance (NOTE 1)	C <sub>J</sub>	240									pF
Typical thermal resistance (NOTE 2)	R <sub>θJA</sub>	80									°C/W
Operating junction temperature range	T <sub>J</sub>	-55 to +125				-55 to +150					°C
Storage temperature range	T <sub>STG</sub>	-55 to +150									°C

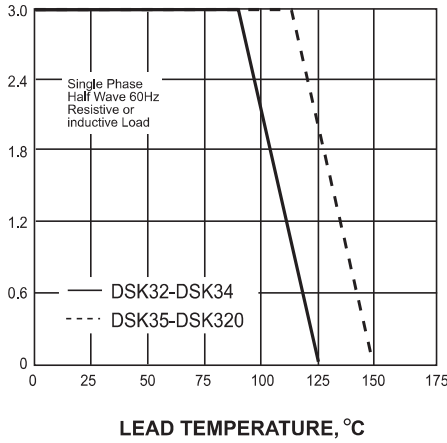
**Note:**1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

### Rating and characteristic curves

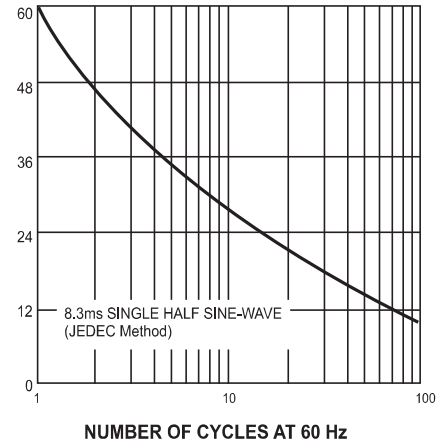
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



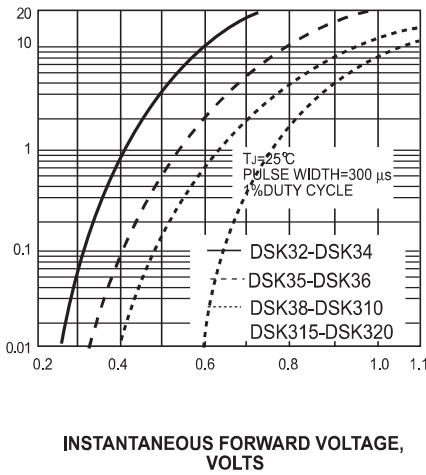
PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



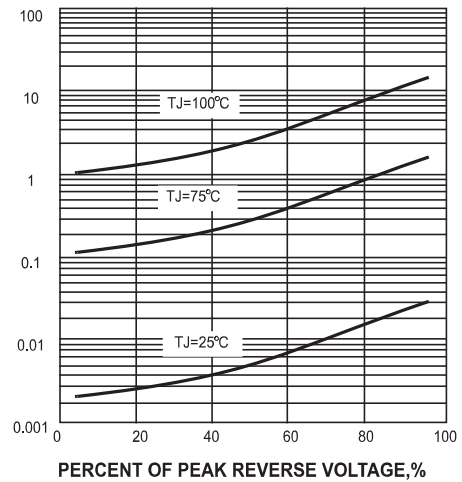
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



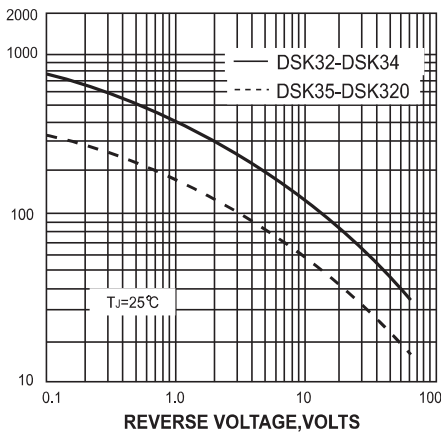
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS





JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



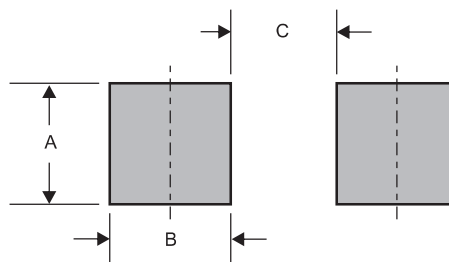
**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

**Marking**

Type number	Marking code
DSK32	K32
DSK33	K33
DSK34	K34
DSK35	K35
DSK36	K36
DSK38	K38
DSK310	K310
DSK315	K315
DSK320	K320

**Suggested solder pad layout**

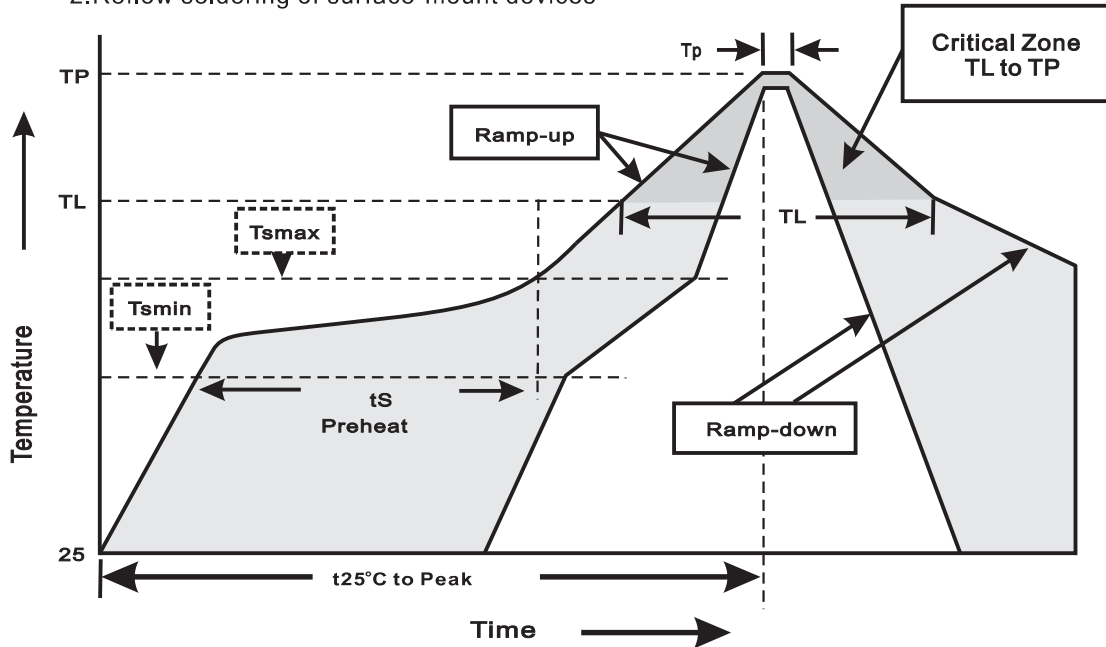


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)

**Suggested thermal profiles for soldering processes**

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat -Temperature Min(T <sub>smín</sub> ) -Temperature Max(T <sub>smáx</sub> ) -Time(min to max)(t <sub>s</sub> )	150°C 200°C 60~120sec
T <sub>smáx</sub> to T <sub>L</sub> -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T <sub>L</sub> ) -Time(t <sub>L</sub> )	217°C 60~260sec
Peak Temperature(T <sub>P</sub> )	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t <sub>P</sub> )	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes